

R-C Thermal Model Parameters

DESCRIPTION

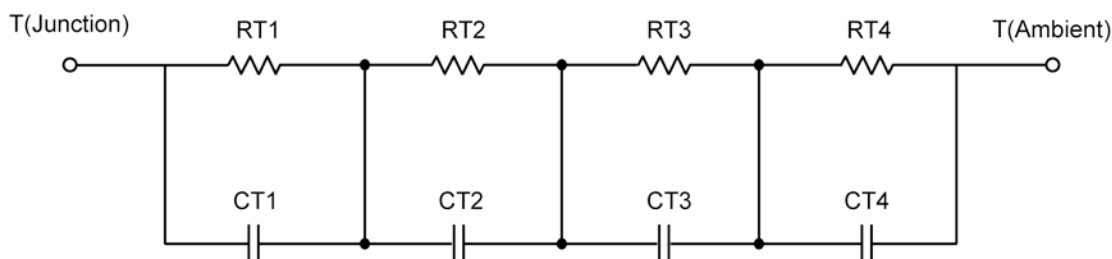
The parametric values in the R-C thermal model have been derived using curve-fitting techniques. These techniques are described in "[A Simple Method of Generating Thermal Models for a Power MOSFET](#)"[1]. When implemented in P-Spice, these values have matching characteristic curves to the Single Pulse Transient Thermal Impedance curves for the MOSFET.

R-C values for the electrical circuit in the Foster/Tank and Cauer/Filter configurations are included.

Note:

For a detailed explanation of implementing these values in P-SPICE, refer to [Application Note AN609 Thermal Simulations Of Power MOSFETs on P-SPICE Platform](#).

R-C THERMAL MODEL FOR TANK CONFIGURATION



R-C VALUES FOR TANK CONFIGURATION			
Thermal Resistance (°C/W)			
Junction to	Ambient	Case Drain Top	Case Source
RT1	800.8191 m	13.7052 m	239.2233 m
RT2	7.3171	516.9776 m	2.4371
RT3	10.5922	286.2836 m	21.5624 m
RT4	49.1350	182.6087 m	4.3831 m
Thermal Capacitance (Joules/°C)			
Junction to	Ambient	Case Drain Top	Case Source
CT1	10.0497 m	253.9448 u	1.7223 m
CT2	588.1963 m	31.9162 m	27.9777 m
CT3	47.1217 m	69.2346 m	1.0998
CT4	1.4789	3.3324 m	6.1924 m

This document is intended as a SPICE modeling guideline and does not constitute a commercial product data sheet. Designers should refer to the appropriate data sheet of the same number for guaranteed specification limits.

R-C THERMAL MODEL FOR FILTER CONFIGURATION**R-C VALUES FOR FILTER CONFIGURATION**

Thermal Resistance (°C/W)			
Junction to	Ambient	Case Drain Top	Case Source
RF1	8.6804	311.1249 m	290.1786 m
RF2	5.8765	964.2920 n	1.2842
RF3	5.9897	5.0643 m	1.0355
RF4	47.2176	679.7321 m	93.5467 m
Thermal Capacitance (Joules/°C)			
Junction to	Ambient	Case Drain Top	Case Source
CF1	25.1275 m	3.2342 m	1.6895 m
CF2	145.2098 m	4.8515 m	25.2933 m
CF3	17.5646 m	15.5525 m	2.7409 m
CF4	1.2744	2.8720 m	277.7597 m

Note: NA indicates not applicable

Reference:

[1] "A Simple Method of Generating Thermal Models for a Power MOSFET" by Wharton McDaniel and Kandarp Pandya. IEEE / SEMITHERM 2002

